



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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# MALS068

## Silicon planar type

For ESD protection

### ■ Features

- Electrostatic discharge ESD:  $\pm 30$  kV
- SS-Mini 2 pin molde type package, optimum for high-density mounting.

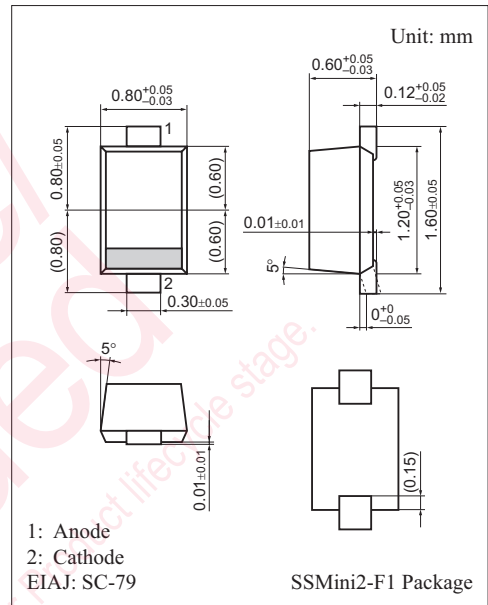
### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Total power dissipation *1	$P_T$	150	mW
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$
Electrostatic discharge *2	ESD	$\pm 30$	kV

Note) \*1:  $P_T = 150$  mW achieved with a printed circuit board.

\*2: Test method: IEC61000-4-2

(C = 150 pF, R = 330  $\Omega$ , Contact discharge: 10 times)



Marking Symbol: RE

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

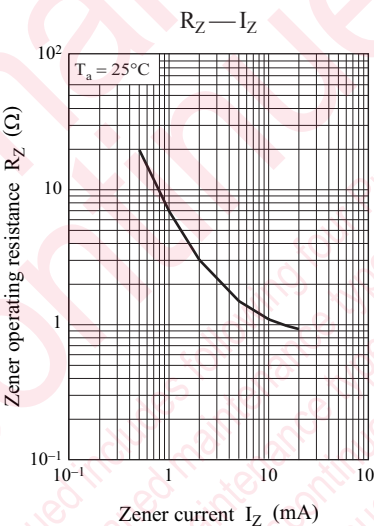
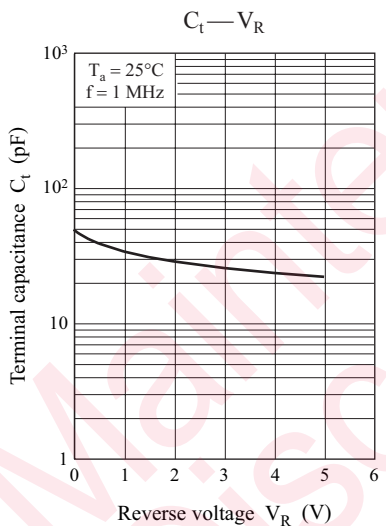
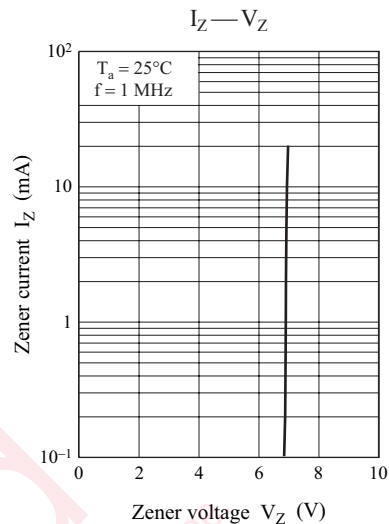
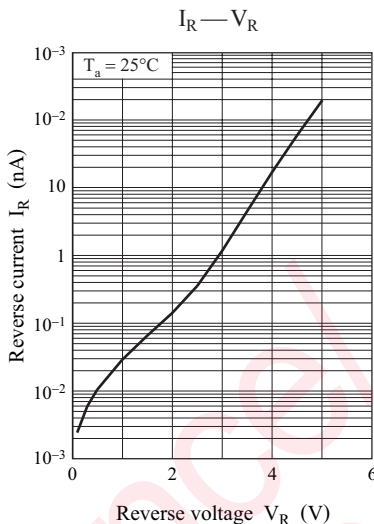
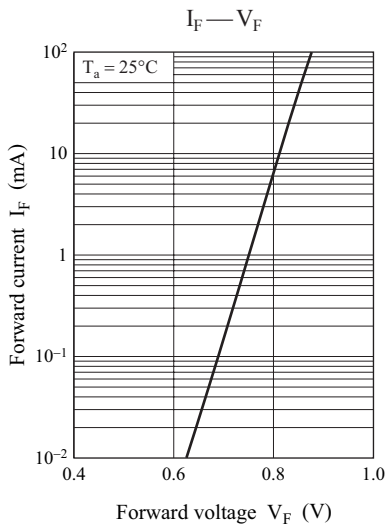
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Breakdown voltage *	$V_{BR}$	$I_R = 5$ mA	6.4	6.8	7.2	V
Reverse current	$I_R$	$V_R = 4.0$ V			0.5	$\mu\text{A}$
Terminal capacitance	$C_t$	$V_R = 0$ V, $f = 1$ MHz		50		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. The temperature must be controlled  $25^\circ\text{C}$  for  $V_{BR}$  measurement.

$V_{BR}$  value measured at other temperature must be adjusted to  $V_{BR}(25^\circ\text{C})$

3. \*:  $V_{BR}$  guaranteed 20 ms after current flow.





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